

Lonten N-channel 650V, 2A Power MOSFET

Description

The Power MOSFET is fabricated using the advanced planer VDMOS technology. The resulting device has low conduction resistance, superior switching performance and high avalanche energy.

Features

- ◆ Low $R_{DS(on)}$
- ◆ Low gate charge (typ. $Q_g = 10.2 \text{ nC}$)
- ◆ 100% UIS tested
- ◆ RoHS compliant

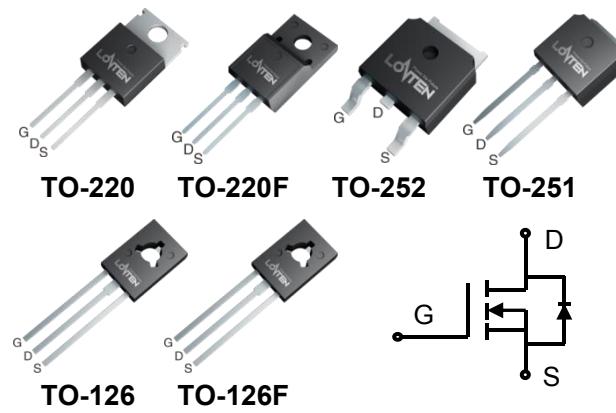
Applications

- ◆ Power factor correction.
- ◆ Switched mode power supplies.
- ◆ LED driver.

Product Summary

V_{DSS}	650V
I_D	2A
$R_{DS(on),max}$	5.2Ω

$Q_{g,typ}$ 10.2 nC



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	650	V
Continuous drain current ($T_c = 25^\circ\text{C}$) ($T_c = 100^\circ\text{C}$)	I_D	2 1.3	A A
Pulsed drain current ¹⁾	I_{DM}	8	A
Gate-Source voltage	V_{GSS}	± 30	V
Avalanche energy, single pulse ²⁾	E_{AS}	80	mJ
Peak diode recovery dv/dt ³⁾	dv/dt	5	V/ns
Power Dissipation TO-220F\TO-126 ($T_c = 25^\circ\text{C}$) Derate above 25°C	P_D	27 0.22	W W/ $^\circ\text{C}$
Power Dissipation TO-220\ TO-251\ TO-252 ($T_c = 25^\circ\text{C}$) Derate above 25°C		35 0.28	W W/ $^\circ\text{C}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$
Continuous diode forward current	I_S	2	A
Diode pulse current	$I_{S,pulse}$	8	A

Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO-220F\TO-126	TO-220\TO-251\TO-252	
Thermal resistance, Junction-to-case	$R_{\theta JC}$	4.63	3.57	$^\circ\text{C/W}$
Thermal resistance, Junction-to-ambient	$R_{\theta JA}$	100	62	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube	Units/Reel
LNC2N65	TO-220	LNC2N65	50	
LND2N65	TO-220F	LND2N65	50	
LNG2N65	TO-252	LNG2N65		2500
LNH2N65	TO-251	LNH2N65	72	
LNU2N65	TO-126	LNU2N65	50	
LNV2N65	TO-126F	LNV2N65	50	

Electrical Characteristics

T_c = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =0.25 mA	650	-	-	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =0.25 mA	2	-	4	V
Drain cut-off current	I _{DSS}	V _{DS} =650 V, V _{GS} =0 V, T _j = 25°C T _j = 125°C	-	-	1	μA
Gate leakage current, Forward	I _{GSSF}	V _{GS} =30 V, V _{DS} =0 V	-	-	100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-30 V, V _{DS} =0 V	-	-	-100	nA
Drain-source on-state resistance	R _{D(on)}	V _{GS} =10 V, I _D =1 A	-	4.2	5.2	Ω
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	-	338	-	pF
Output capacitance	C _{oss}		-	36	-	
Reverse transfer capacitance	C _{rss}		-	3.4	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 325 V, I _D = 2 A R _G = 10 Ω, V _{GS} =15 V	-	17.2	-	ns
Rise time	t _r		-	35.6	-	
Turn-off delay time	t _{d(off)}		-	33.9	-	
Fall time	t _f		-	29	-	
Gate charge characteristics						
Gate to source charge	Q _{gs}	V _{DD} =520 V, I _D =2 A, V _{GS} =0 to 10 V	-	2.6	-	nC
Gate to drain charge	Q _{gd}		-	4.7	-	
Gate charge total	Q _g		-	10.2	-	
Gate plateau voltage	V _{plateau}		-	5	-	
Reverse diode characteristics						
Diode forward voltage	V _{SD}	V _{GS} =0 V, I _F =2 A	-	-	1.5	V
Reverse recovery time	t _{rr}	V _R =400 V, I _F =2 A, dI _F /dt=100 A/μs	-	221.8	-	ns
Reverse recovery charge	Q _{rr}		-	0.75	-	
Peak reverse recovery current	I _{rrm}		-	7.4	-	

Notes:

1. Pulse width limited by maximum junction temperature.
2. L=10mH, I_{AS} = 4A, Starting T_j= 25°C.
3. I_{SD} = 2A, di/dt≤100A/us, V_{DD}≤BV_{DS}, Starting T_j= 25°C.

Electrical Characteristics Diagrams

Figure 1. Typical Output Characteristics

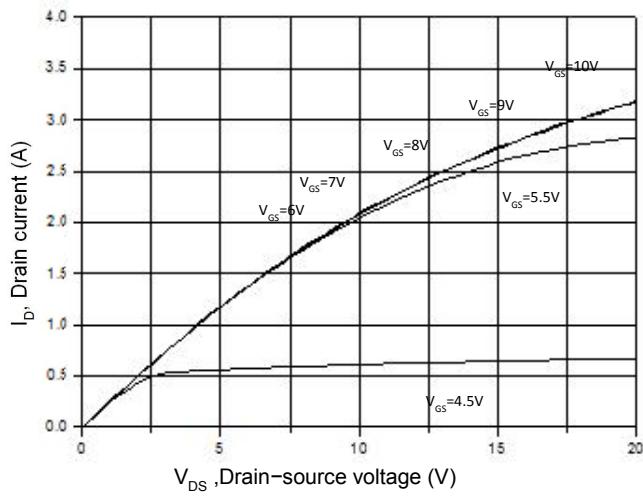


Figure 2. Transfer Characteristics

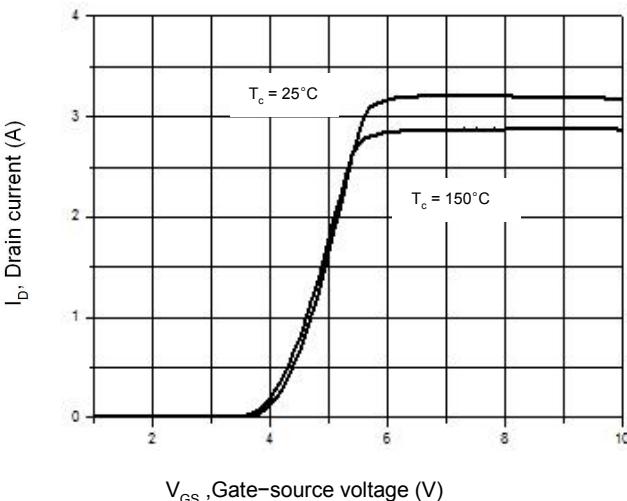


Figure 3. On-Resistance Variation vs. Drain Current

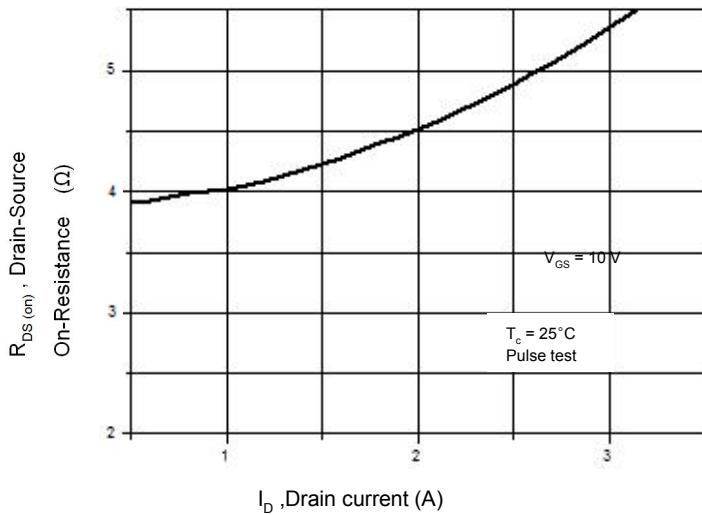


Figure 4. Threshold Voltage vs. Temperature

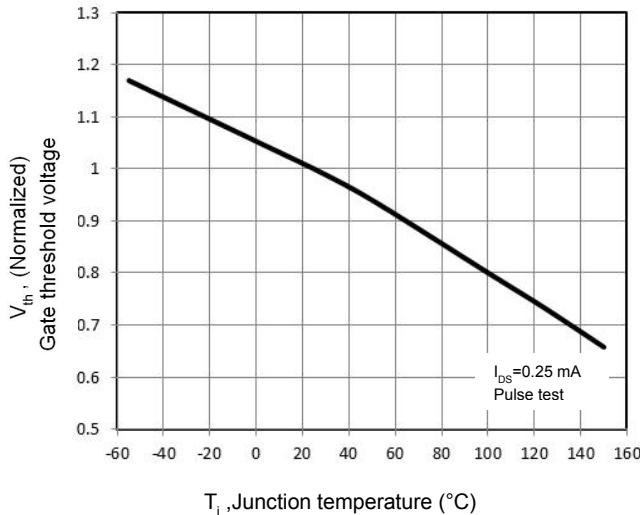


Figure 5. Breakdown Voltage vs. Temperature

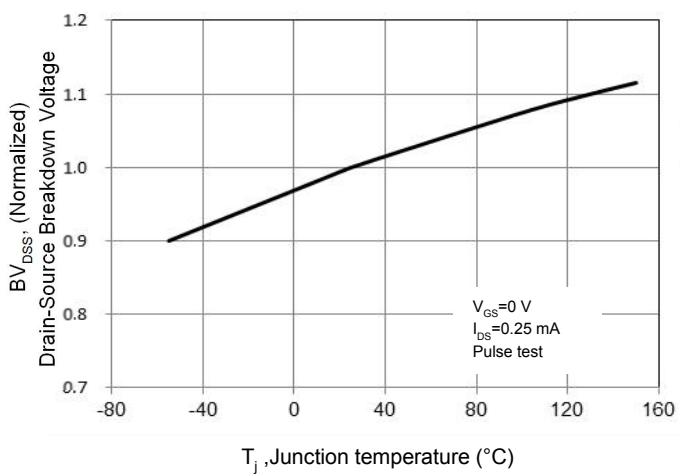


Figure 6. On-Resistance vs. Temperature

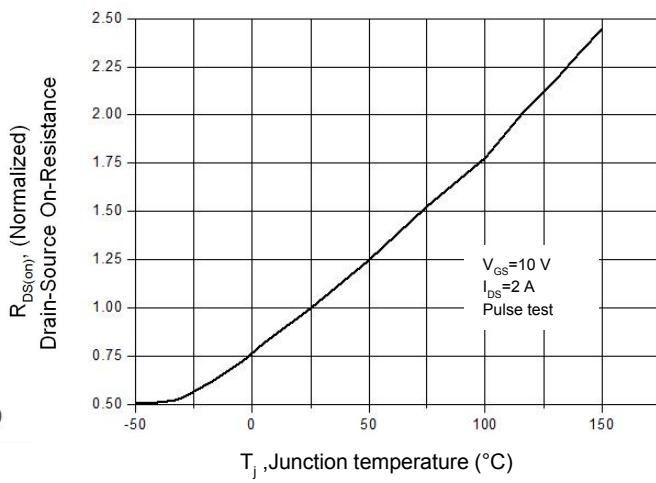


Figure 7. Capacitance Characteristics

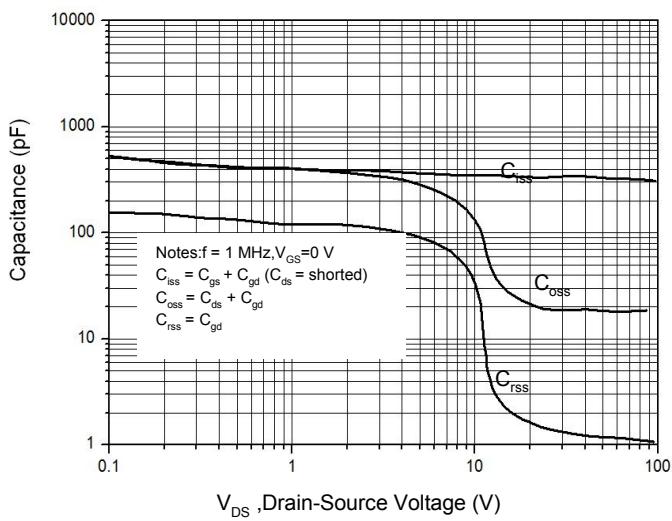


Figure 9. Maximum Safe Operating Area

TO-220F

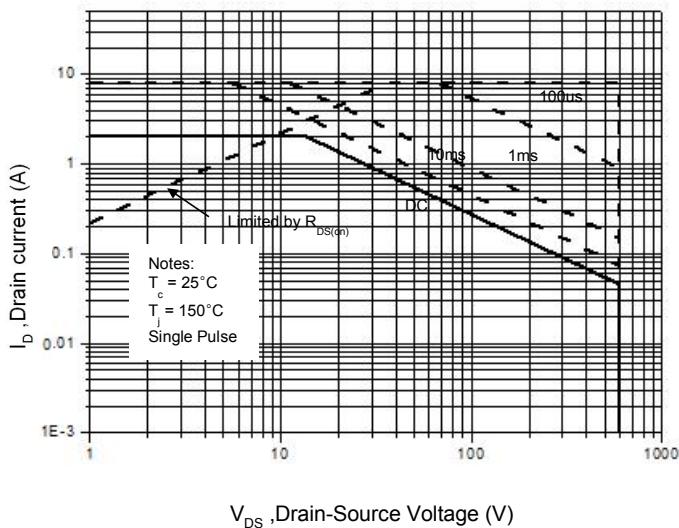


Figure 11. Power Dissipation vs. Temperature

TO-220F/TO-126

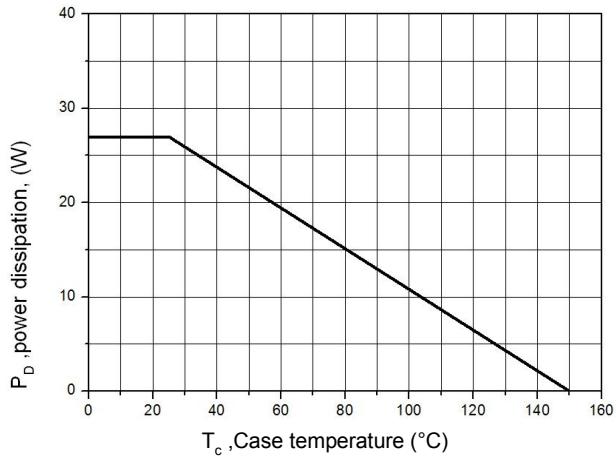


Figure 8. Gate Charge Characterist

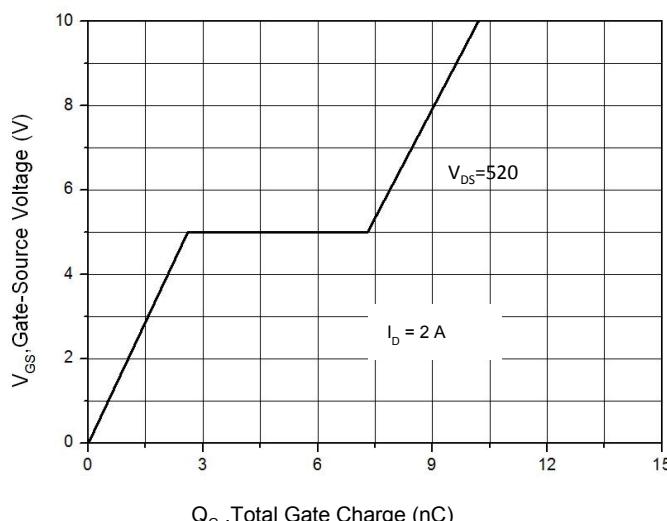


Figure 10. Maximum Safe Operating Area

TO-220/ TO-251/TO-252

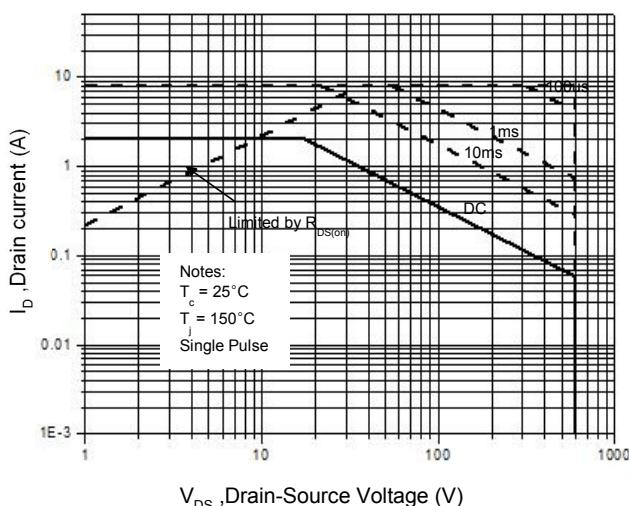


Figure 12. Power Dissipation vs. Temperature

TO-220/ TO-251/TO-252

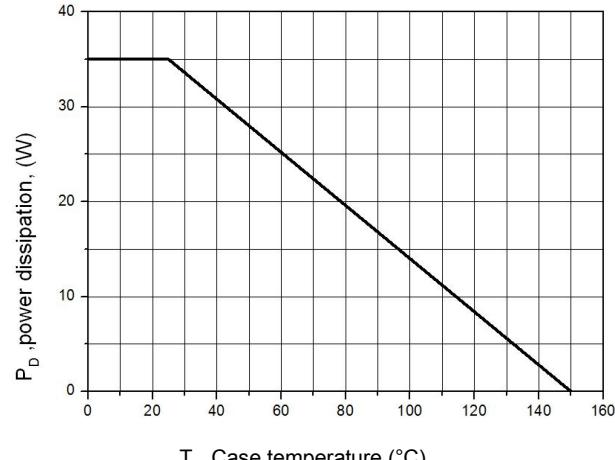


Figure 13. Continuous Drain Current vs. Temperature

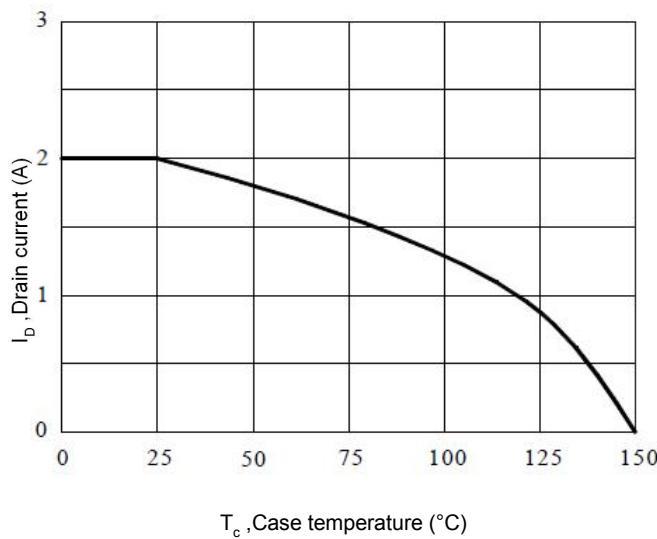


Figure 14. Body Diode Transfer Characteristics

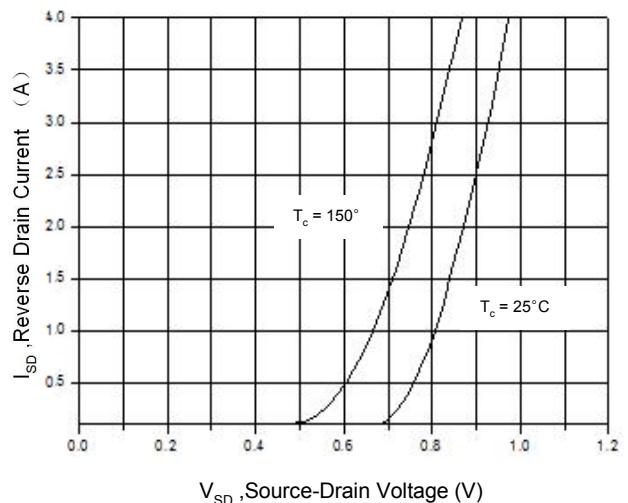


Figure 15 Transient Thermal Impedance, Junction to Case, TO-220F/TO-126

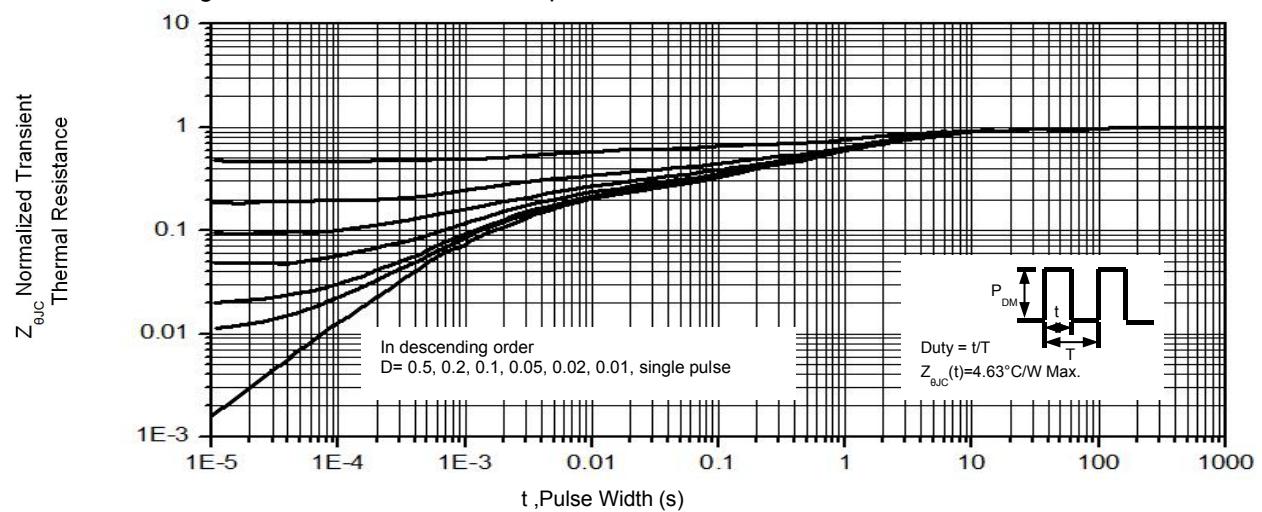
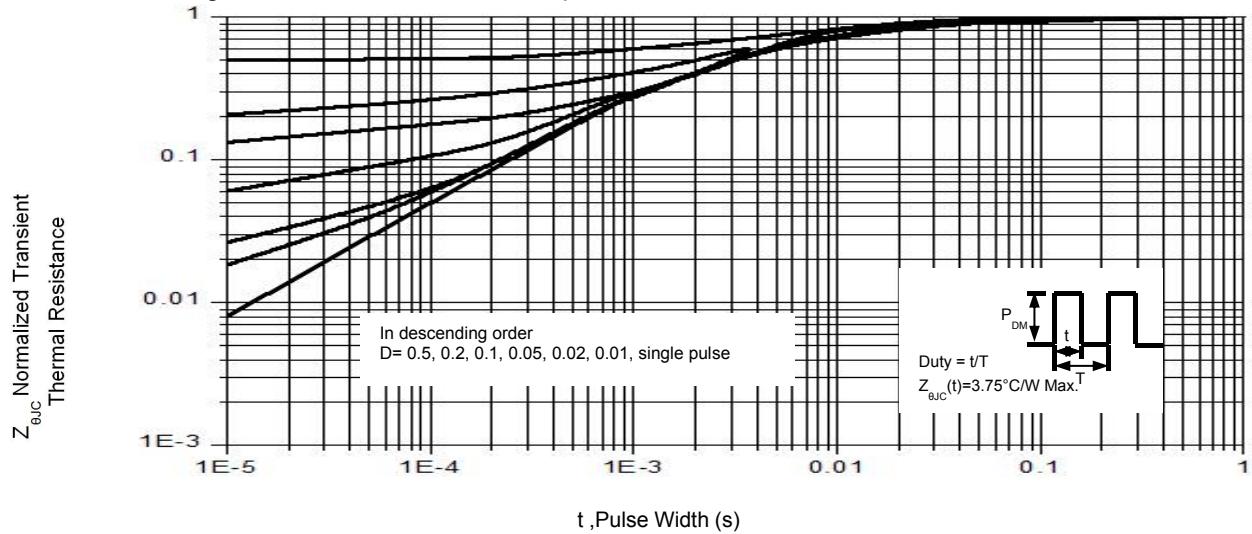
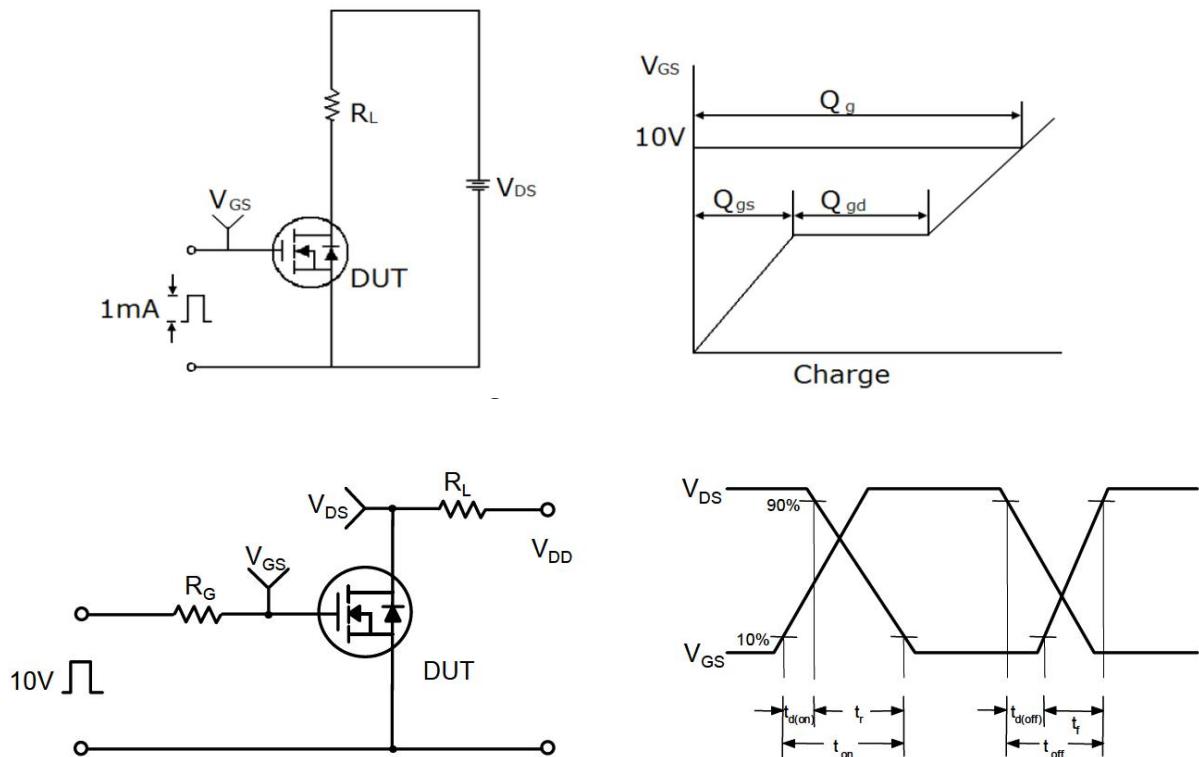


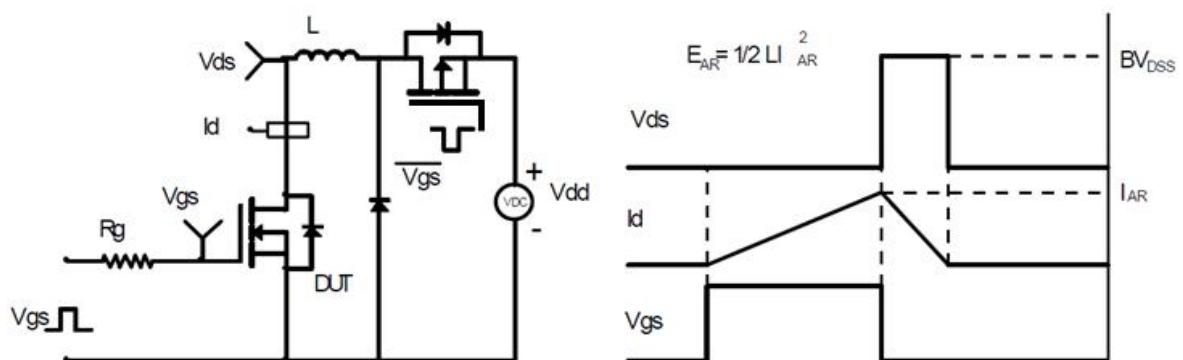
Figure 16. Transient Thermal Impedance, Junction to Case, TO-220/ TO-251/TO-252



Gate Charge Test Circuit & Waveform



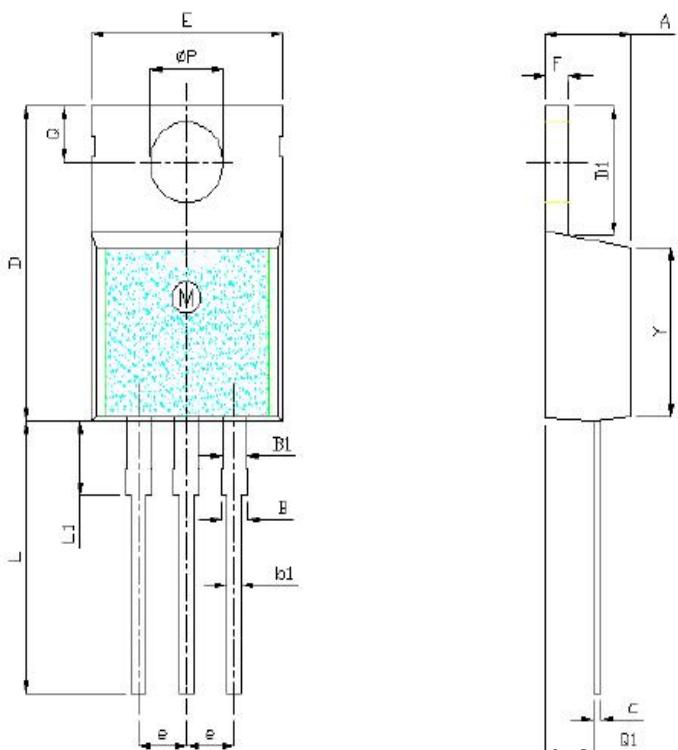
Unclamped Inductive Switching Test Circuit & Waveforms



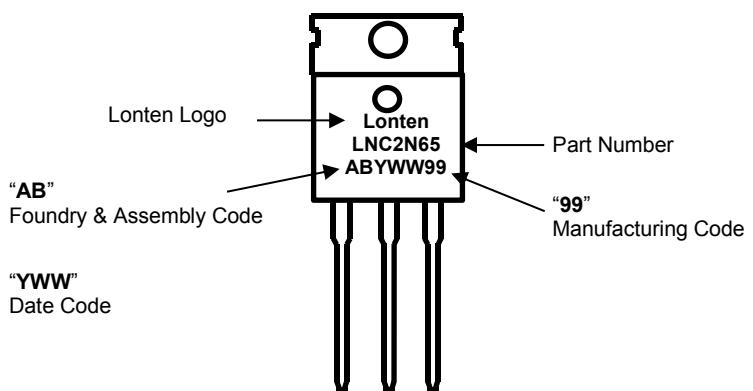
Mechanical Dimensions for TO-220

UNIT: mm

SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	4		4.8	e	2.44	2.54	2.64
B	1.2		1.4	F	1.1		1.4
B1	1		1.4	L	12.5		14.5
b1	0.75		0.95	L1	3	3.5	4
c	0.4		0.55	ΦP	3.7	3.8	3.9
D	15		16.5	Q	2.5		3
D1	5.9		6.9	Q1	2		2.9
E	9.9		10.7	Y	8.02	8.12	8.22



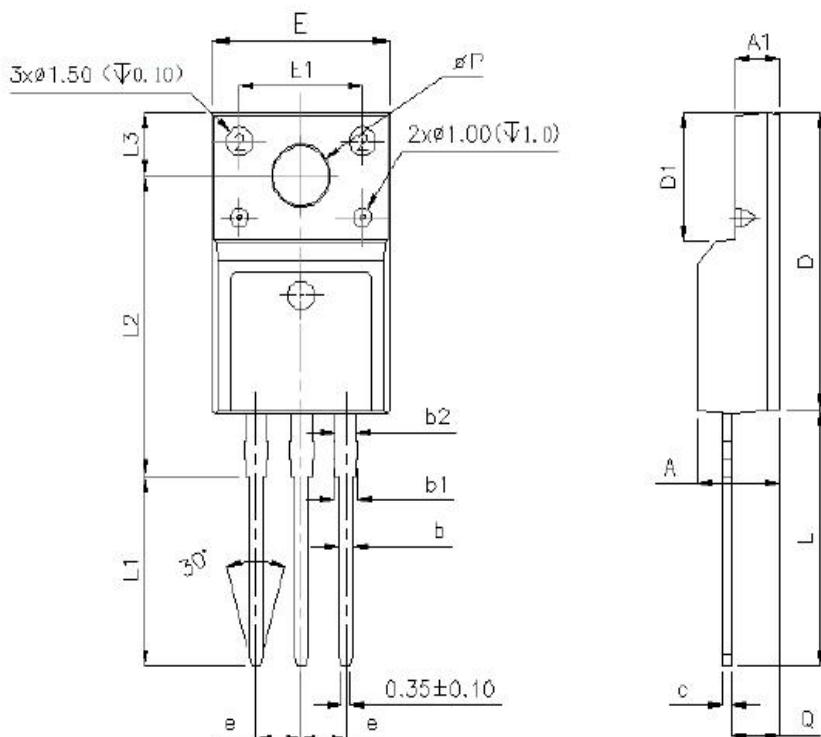
TO-220 Part Marking Information



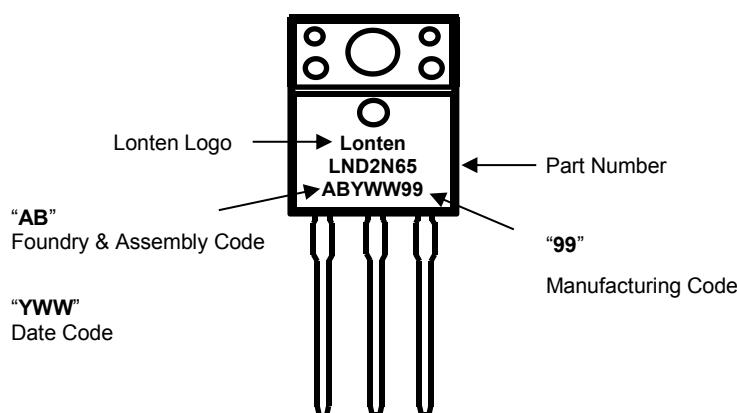
Mechanical Dimensions for TO-220F

UNIT: mm

SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	4.5		4.9	E1	6.5	7	7.5
A1	2.3		2.9	e	2.44	2.54	2.64
b	0.65		0.9	L	12.5		14.3
b1	1.1		1.7	L1	9.45		10.05
b2	1.2		1.4	L2	15		16
c	0.35		0.65	L3	3.2		4.4
D	14.5		16.5	ΦP	3		3.3
D1	6.1		6.9	Q	2.5		2.9
E	9.6		10.3				



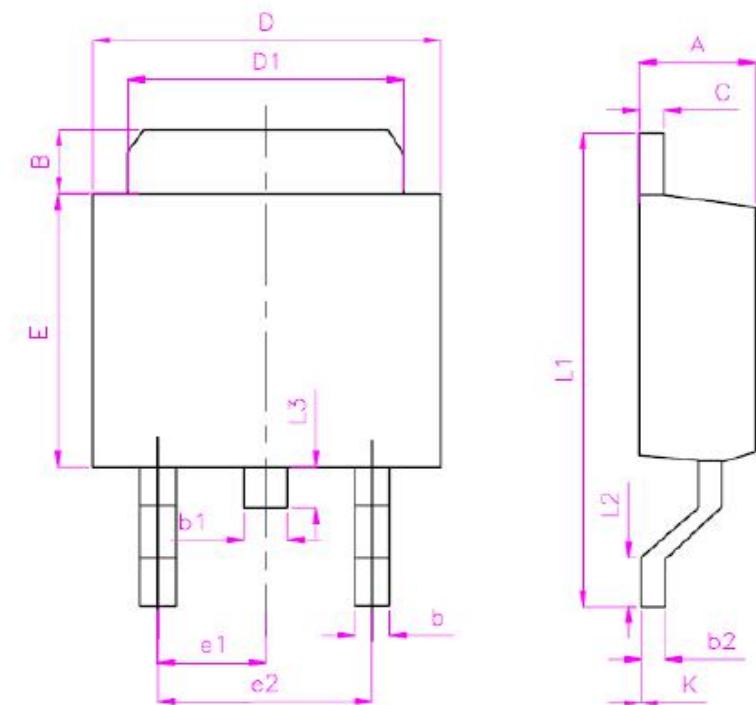
TO-220F Part Marking Information



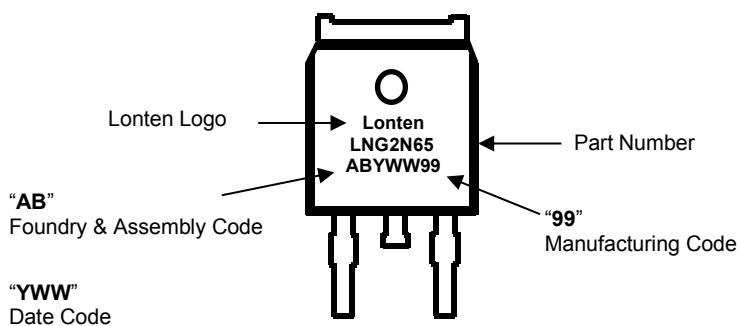
Mechanical Dimensions for TO-252

UNIT: mm

SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	2.10		2.50	E	5.80		6.30
B	0.80		1.25	e1	2.25	2.30	2.35
b	0.50		0.85	e2	4.45		4.75
b1	0.50		0.90	L1	9.50		10.20
b2	0.45		0.60	L2	0.90		1.45
C	0.45		0.60	L3	0.60		1.10
D	6.35		6.75	K	-0.1		0.10
D1	5.10		5.50				



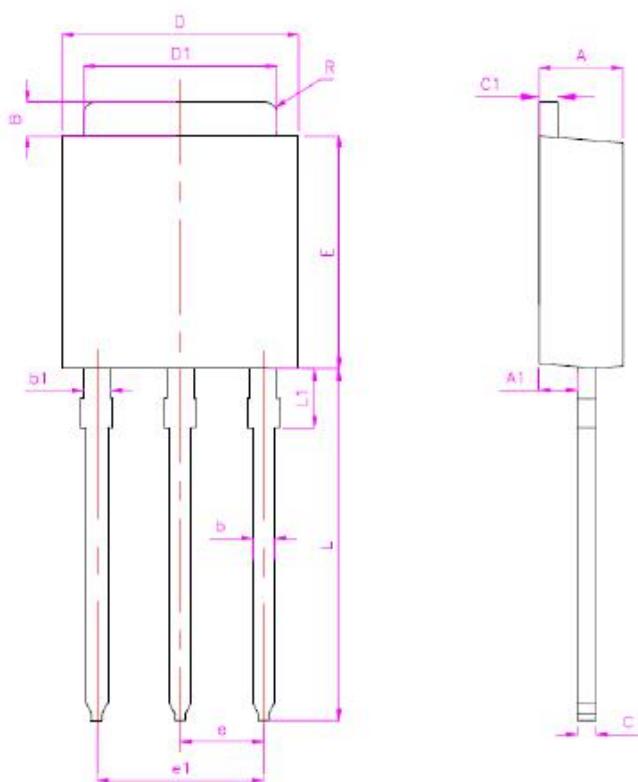
TO-252 Part Marking Information



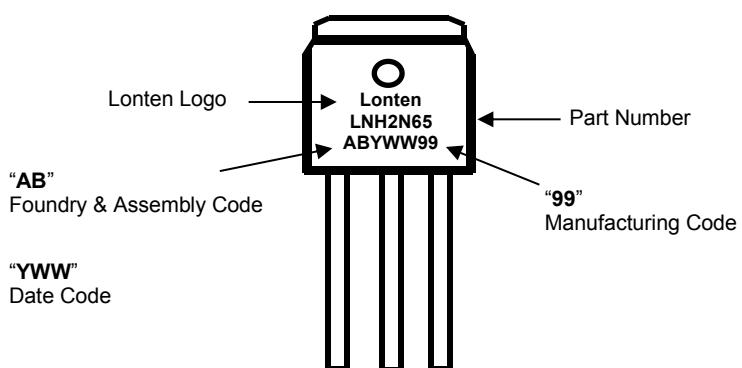
Mechanical Dimensions for TO-251

UNIT: mm

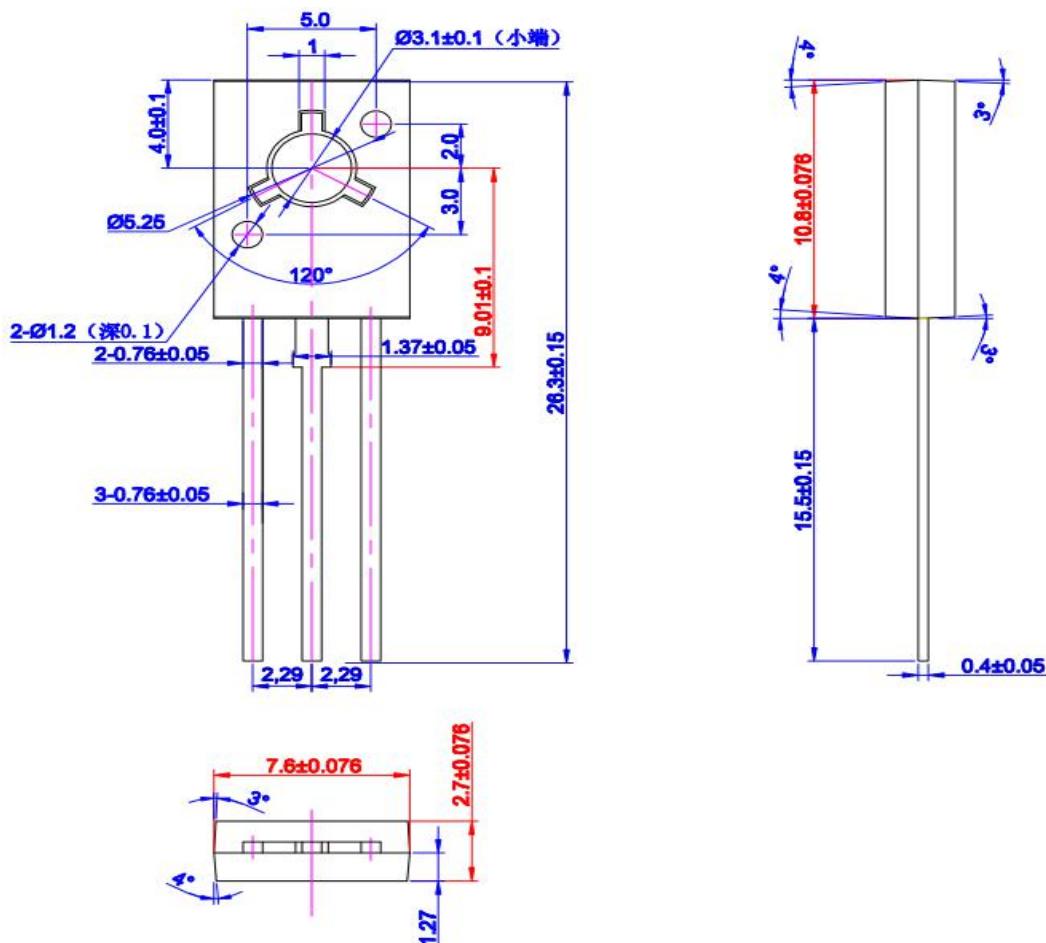
SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	2.10		2.50	D1	5.10		5.50
A1	0.95		1.30	E	5.80		6.30
B	0.80		1.25	e	2.25	2.30	2.35
b	0.50		0.80	L	7.70		8.50
b1	0.70		0.90	L1	1.45		1.95
C	0.45		0.60	R		0.30	
C1	0.45		0.60				
D	6.35		6.75				



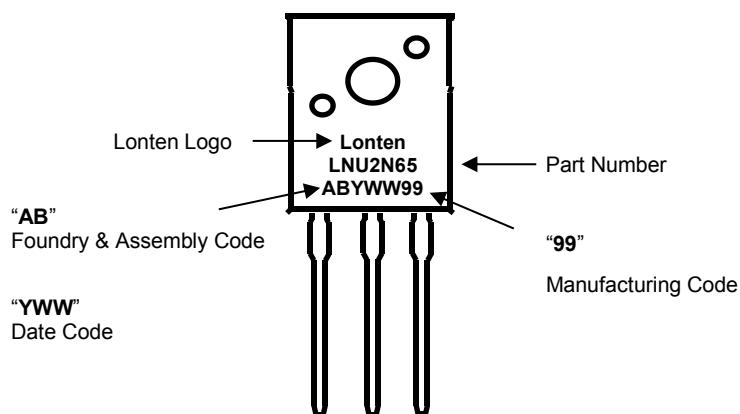
TO-251 Part Marking Information



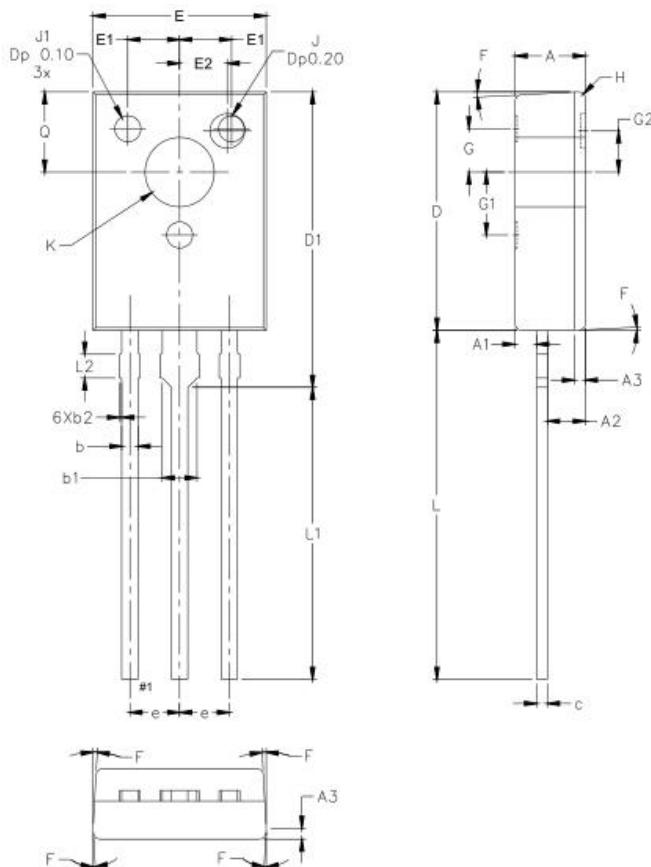
Mechanical Dimensions for TO-126:(unit:mm)



TO-126 Part Marking Information

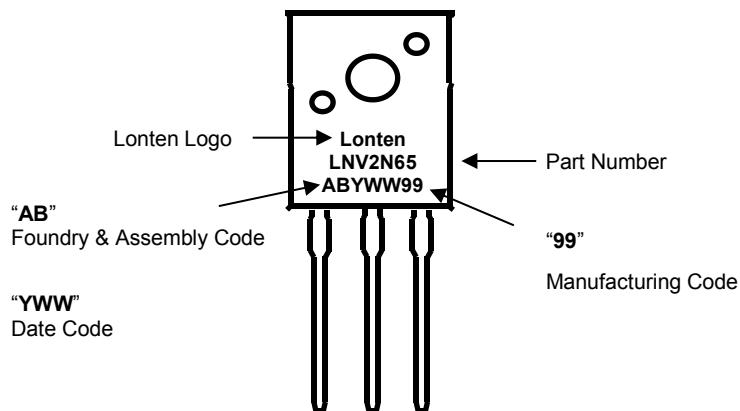


Mechanical Dimensions for TO-126F:(unit:mm)



SYMBOL	MIN	MAX	SYMBOL	MIN	MAX
A	3.05	3.45	e	2.08	2.48
A1	1.00	REF.	F	3°	REF.
A2	1.55	1.95	G	2.00	REF.
A3	0.50	REF.	G1	2.90	REF.
b	0.65	0.85	G2	1.90	REF.
b1	1.50	1.70	H	0.30	REF.
c	0.45	0.60	L	15.90	16.30
D	10.80	11.20	L1	12.76	13.36
D1	-	14.20	L2	1.00	1.20
E	7.70	8.30	K	3.10	3.30
E1	2.40	REF.	Q	3.55	3.85
E2	2.20	REF.	b2	-	0.20
J	1.60	REF.	J1	1.20	REF.

TO-126F Part Marking Information



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